Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application

Listing of Claims:

1.-36. (Canceled)

37. (Currently Amended) A clad board for forming circuitry, the clad board being manufactured by:

sticking a releasing film to a pre-preg sheet;

forming a hole in the pre-preg sheet with the releasing film, the hole being one of a non-through-hole and a through-hole;

filling the hole with conductive paste;

peeling off the releasing film; and

heating and pressing a metal foil onto the pre-preg sheet,

wherein said clad board comprises:

a fiber sheet included in the pre-preg sheet, the fiber sheet comprising a non-woven fabric and a resin material impregnated into the fiber sheet, the resin material comprising at least one of a thermoplastic resin and a thermosetting resin having a semi-cured portion, the fiber sheet having a top surface and a bottom surface; and

a resin layer formed smoothly on both the top surface and the bottom surface of the fiber sheet, the resin layer being made of material identical to the resin material; and

wherein the fiber sheet comprises:

an inside layer having two faces and two surface layers, one of which surface layers is disposed on each face of the inside layer;

~~a first surface and a second surface,~~

~~a first layer disposed at the first surface of the fiber sheet,~~

~~a second layer, and~~

~~a third layer disposed at the second surface of the fiber sheet, the second layer being located between the first layer and the third layer,~~ and

wherein the density of the non-woven fabric in the inside ~~second~~ layer is lower than the density of the non-woven fabric in each of the surface layers ~~first layer and lower than the density of the third layer~~.

38.-39. (Canceled)

40. (Previously Presented) The clad board of claim 37, wherein the fiber sheet has a density ranging from 700 kg/m³ to 1000 kg/m^3.

41.-58. (Canceled)

59. (Currently Amended) The clad board of claim 37,

wherein the fiber sheet has a hole formed therein, said clad board further comprising a conductive paste filling the hole of the fiber sheet, the conductive paste ~~including~~ comprising non-spherical-shaped conductive particles.

60.-75. (Canceled)

76. (Currently Amended) A core board for a clad board for forming circuitry, the core board comprising:

a fiber sheet;

the fiber sheet comprising a non-woven fabric and a resin material impregnated into the fiber sheet, the resin material comprising at least one of a thermoplastic resin and a thermoplastic resin having a semi-cured portion, the fiber sheet having a top surface and a bottom surface;

and

a resin layer formed on both the top surface and the bottom surface of the fiber sheet, the resin layer being made of material identical to the resin material;

wherein the fiber sheet ~~includes;~~ comprises:

an inside layer having two faces and two surface layers, one which surface layers is disposed on each face of the inside layer; and

wherein the density of the non-woven fabric in the inside layer is lower than the density of the non-woven fabric in each if the surface layers

~~first and second layers disposed at respective outermost sides of the fiber sheet; and~~

~~a third layer located between the first and second layers, the third layer having a density lower than respective densities of the first and second layers~~.

77.-83. (Canceled)

84. (Currently Amended) The ~~clad~~ core board of claim ~~47~~ 76, wherein the fiber sheet has a hole formed therein, said ~~clad~~ core board further comprising a conductive paste filling the hole of the fiber sheet, the conductive paste comprising non-spherical-shaped conductive particles.

85. (Previously Presented) The core board of claim 76, wherein the fiber sheet has a density ranging from 700 kg/m^3 to 1000 kg/m^3.

86. (Previously Presented) The clad board of claim 37, wherein the resin material impregnated into the fiber sheet comprises the thermosetting resin having a semi-cured portion.

87. (Currently Amended) The core board of claim ~~66~~ 76, wherein the resin material impregnated into the fiber sheet comprises the thermosetting resin having a semi-cured portion.

88.-95. (Canceled)

96. (New) The clad board of claim 37, wherein the impregnated resin comprises 51 weight% to 54 weight% of the pre-preg sheet.

97. (New) The core board of claim 76, wherein the impregnated resin comprises 51 weight% to 54 weight% of the pre-preg sheet.

98. (New) The clad board of claim 37, wherein the non-woven fabric is an aramid fiber non-woven fabric.

99. (New) The clad board of claim 98, wherein the density of the non-woven fabric in the inner layer is from 500 to 700 kg/m^3 and the density of the non-woven fabric in each of the surface layers is 700 to 1000 kg/m^3.

100. (New) The clad board of claim 37, wherein the density of the non-woven fabric in the inner layer is from 500 to 700 kg/m^3 and the density of the non-woven fabric in each of the surface layers is 700 to 1000 kg/m^3.

101. (New) The core board of claim 76, wherein the non-woven fabric is an aramid fiber non-woven fabric.

102. (New) The core board of claim 101, wherein the density of the non-woven fabric in the inner layer is from 500 to 700 kg/m^3 and the density of the non-woven fabric in each of the surface layers is 700 to 1000 kg/m^3.

103. (New) The core board of claim 76, wherein the density of the non-woven fabric in the inner layer is from 500 to 700 kg/m^3 and the density of the non-woven fabric in each of the surface layers is 700 to 1000 kg/m^3.